

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

KUROSAWA, Miki, et al.

Division of

Appl. No.: 09/549,498

Group Art Unit: Not Yet Assigned

Confirmation No.: Not Yet Assigned

Examiner: Not Yet Assigned

Filed: Concurrently Herewith

For: LASER BEAM MACHINING METHOD FOR WIRING BOARD, LASER BEAM
MACHINING APPARATUS FOR WIRING BOARD, AND CARBONIC ACID GAS
LASER OSCILLATOR FOR MACHINING WIRING BOARD

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Delete the paragraph bridging pages 2, 3, and 4, and insert:

In the prior art, a machining method for the conduction hole includes, for example, drill machining using a rotary milling cutter. Further, a machining method for grooving or cutting for an outside shape includes, for example, router machining using a rotary milling cutter. On the other hand, in recent years, higher density wiring has been desired for higher performance of an electronic device. A more multi-layered and smaller printed board is required to meet the above requirement. Further, it is essential to provide a finer hole diameter of the conduction hole for this purpose. With the current state of the art, the conduction hole is generally provided in the

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